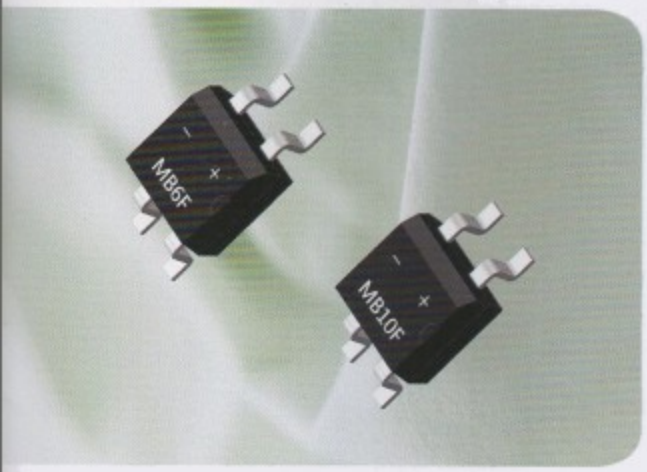
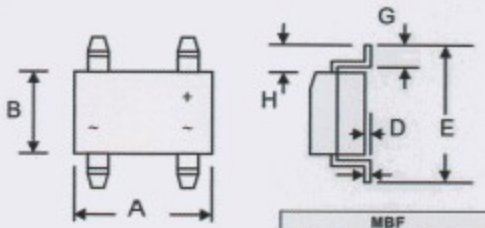
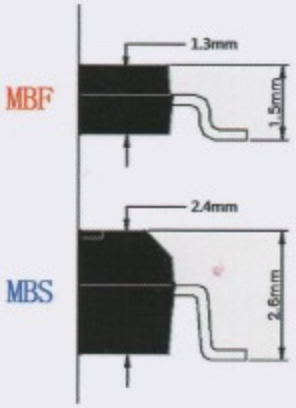
MBF





MBF		
Dim	Min	Max
A	4.50	4.95
B	3.60	4.10
C	0.15	0.35
D	—	0.20
E	6.40	7.00
G	0.50	1.10
H	1.30	1.70
J	1.20	1.60
K	2.30	2.70
L	—	1.80
All Dimensions in mm		



ISO9001质量管理体系 注册编号：00312Q20185R0M
ISO14001环境管理体系 注册编号：00312E10075R0M

产品规格

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS Ratings at 25℃ ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%							
	SYMBOLS	MB2F	MB4F	MB6F	MB8F	MB10F	UINTS
Maximun repetitive reak reverse voltage	V_{RRM}	200	400	600	800	1000	Volts
Maximun RMS voltage	V_{RMS}	140	280	420	560	700	Volts
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	Volts
Maximum average forward rectified currentat On glass-epoxy P.C.B (Note1) On aluminum substrate (Note2)	$I_{F(AV)}$	0.5 0.8					Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30					Amps
Maximum instantaneous forward voltage drop per leg at 0.4A	V_F	1					Volts
Maximum DC reverse current TA=25℃ at rated DC blocking voltage TA=125℃	I_R	5.0 500					μA
Typical junction capactiance per leg (Note3)	C_J	13					pF
Typical thermal resistance per leg	$R_{\theta JA}$	60					℃/W
Operating junction temperature range	T_J	-55 to +150					℃
Storage temperature range	T_{STG}	-55 to +150					℃

Note: 1. On glass epoxy P.C.B. mounted on 0.05 x 0.05 " (1.3 x 1.3mm) pads
2. On aluminum substrate P.C.B. with on area of 0.8 x 0.8" (20 x 20mm) mounted on 0.05 x 0.05" (1.3 x 1.3mm) solder pad
3. Measured at 1.0 MHz and applied reverse voltage of 4.0 volts.